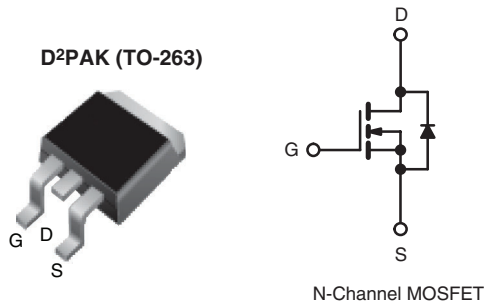


Power MOSFET

PRODUCT SUMMARY

V_{DS} (V)	100	
$R_{DS(on)}$ (Ω)	$V_{GS} = 5$ V	0.27
Q_g (Max.) (nC)	12	
Q_{gs} (nC)	3.0	
Q_{gd} (nC)	7.1	
Configuration	Single	



FEATURES

- Surface Mount
- Available in Tape and Reel
- Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- Logic-Level Gate Drive
- $R_{DS(on)}$ Specified at $V_{GS} = 4$ V and 5 V
- 175°C Operating Temperature

DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The D²PAK (TO-263) is a surface mount power package capable of accommodating die size up to HEX-4. It provides the highest power capability and the lowest possible on-resistance in any existing surface mount package. The D²PAK (TO-263) is suitable for high current applications because of its low internal connection resistance and can dissipate up to 2.0 W in a typical surface mount application.

ORDERING INFORMATION

Package	D ² PAK (TO-263)
SnPb	IRL520S
	SiHL520S

ABSOLUTE MAXIMUM RATINGS $T_C = 25$ °C, unless otherwise noted

PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-Source Voltage	V_{DS}	100	V	
Gate-Source Voltage	V_{GS}	± 10		
Continuous Drain Current	I_D	$T_C = 25$ °C	9.2	A
		$T_C = 100$ °C	6.5	
Pulsed Drain Current ^a	I_{DM}	36	W/°C	
Linear Derating Factor		0.40		
Linear Derating Factor (PCB Mount) ^e		0.025		
Single Pulse Avalanche Energy ^b	E_{AS}	170	mJ	
Avalanche Current ^a	I_{AR}	9.2	A	
Repetitive Avalanche Energy ^a	E_{AR}	6.0	mJ	
Maximum Power Dissipation	P_D	$T_C = 25$ °C	60	W
		$T_A = 25$ °C	3.7	
Peak Diode Recovery dV/dt ^c	dV/dt	5.5	V/ns	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to + 175	°C	
Soldering Recommendations (Peak Temperature)	for 10 s	300 ^d		


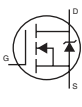
Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- $V_{DD} = 25$ V, starting $T_J = 25$ °C, $L = 3.0$ mH, $R_G = 25$ Ω , $I_{AS} = 9.2$ A (see fig. 12).
- $I_{SD} \leq 9.2$ A, $dI/dt \leq 110$ A/ μ s, $V_{DD} \leq V_{DS}$, $T_J \leq 175$ °C.
- 1.6 mm from case.
- When mounted on 1" square PCB (FR-4 or G-10 material).

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	62	°C/W
Maximum Junction-to-Ambient (PCB Mount) ^a	R_{thJA}	-	40	
Maximum Junction-to-Case (Drain)	R_{thJC}	-	2.5	

Note

a. When mounted on 1" square PCB (FR-4 or G-10 material).

SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$		100	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^\circ\text{C}$, $I_D = 1\text{ mA}$		-	0.12	-	V/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$		1.0	-	2.0	V
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 10\text{ V}$		-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 100\text{ V}, V_{GS} = 0\text{ V}$		-	-	25	μA
		$V_{DS} = 80\text{ V}, V_{GS} = 0\text{ V}, T_J = 150\text{ }^\circ\text{C}$		-	-	250	
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 5\text{ V}$	$I_D = 5.5\text{ A}^b$	-	-	0.27	Ω
		$V_{GS} = 4\text{ V}$	$I_D = 4.6\text{ A}^b$	-	-	0.38	Ω
Forward Transconductance	g_{fs}	$V_{DS} = 50\text{ V}, I_D = 5.5\text{ A}^b$		3.2	-	-	S
Dynamic							
Input Capacitance	C_{iss}	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1.0\text{ MHz}$, see fig. 5		-	490	-	pF
Output Capacitance	C_{oss}			-	150	-	
Reverse Transfer Capacitance	C_{rss}			-	30	-	
Total Gate Charge	Q_g	$V_{GS} = 5\text{ V}$	$I_D = 9.2\text{ A}, V_{DS} = 80\text{ V}$, see fig. 6 and 13 ^b	-	-	12	nC
Gate-Source Charge	Q_{GS}			-	-	3.0	
Gate-Drain Charge	Q_{GD}			-	-	7.1	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 50\text{ V}, I_D = 9.2\text{ A}, R_G = 9\text{ }\Omega, R_D = 5.2\text{ }\Omega$, see fig. 10 ^b		-	9.8	-	ns
Rise Time	t_r			-	64	-	
Turn-Off Delay Time	$t_{d(off)}$			-	21	-	
Fall Time	t_f			-	27	-	
Dynamic							
Internal Drain Inductance	L_D	Between lead, 6 mm (0.25") from package and center of die contact 		-	4.5	-	nH
Internal Source Inductance	L_S			-	7.5	-	
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p-n junction diode 		-	-	9.2	A
Pulsed Diode Forward Current ^a	I_{SM}			-	-	36	
Body Diode Voltage	V_{SD}	$T_J = 25\text{ }^\circ\text{C}, I_S = 9.2\text{ A}, V_{GS} = 0\text{ V}^b$		-	-	2.5	V
Body Diode Reverse Recovery Time	t_{rr}	$T_J = 25\text{ }^\circ\text{C}, I_F = 9.2\text{ A}, di/dt = 100\text{ A}/\mu\text{s}^b$		-	130	190	ns
Body Diode Reverse Recovery Charge	Q_{rr}			-	0.83	1.0	μC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)					

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
 b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\%$.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

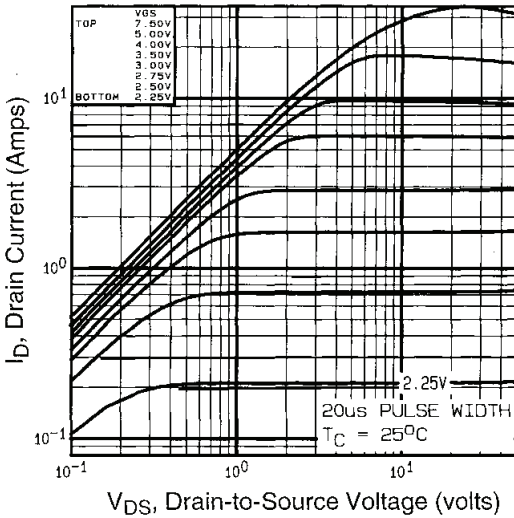


Fig. 1 - Typical Output Characteristics, $T_C = 25\text{ }^\circ\text{C}$

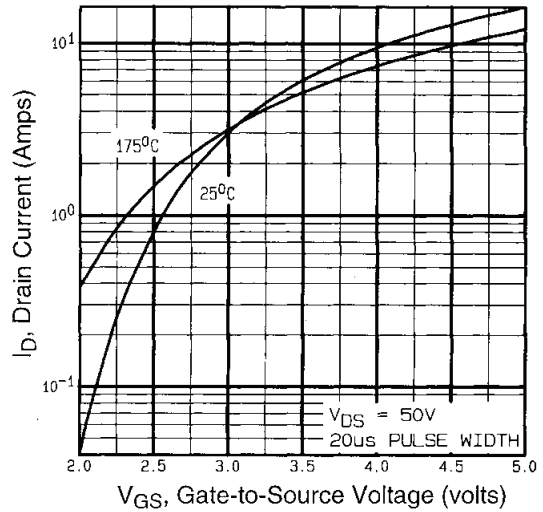


Fig. 3 - Typical Transfer Characteristics

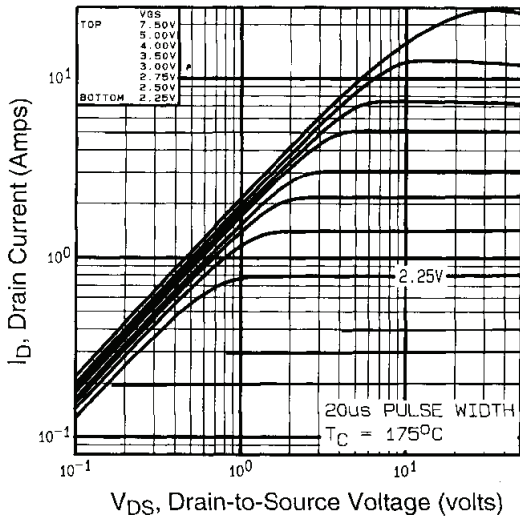


Fig. 2 - Typical Output Characteristics, $T_C = 150\text{ }^\circ\text{C}$

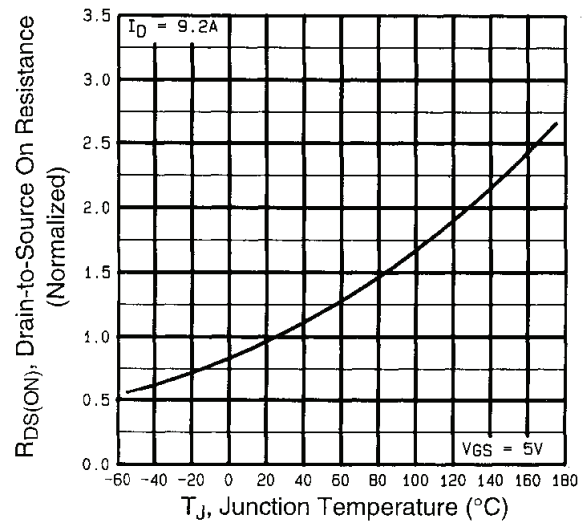


Fig. 4 - Normalized On-Resistance vs. Temperature

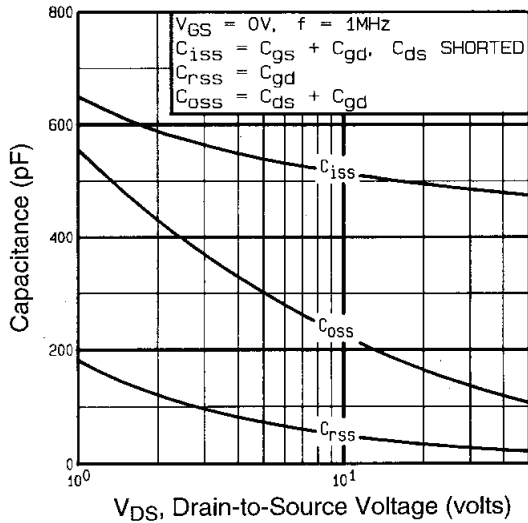


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

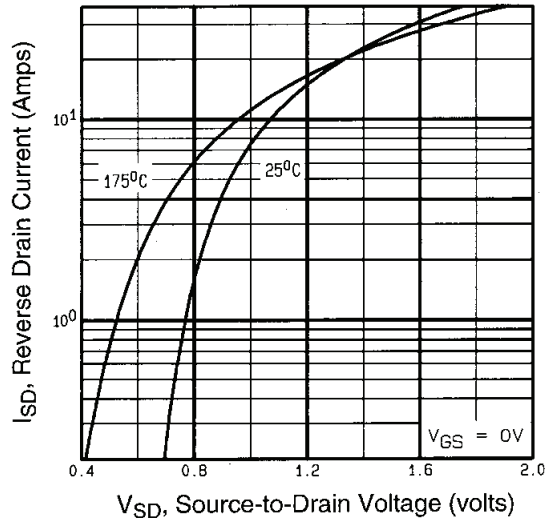


Fig. 7 - Typical Source-Drain Diode Forward Voltage

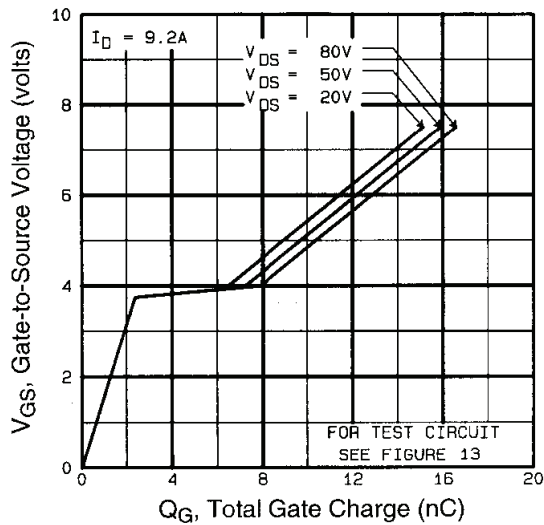


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

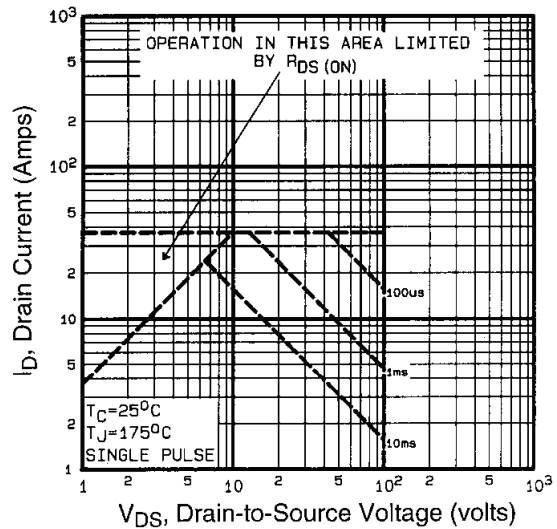


Fig. 8 - Maximum Safe Operating Area

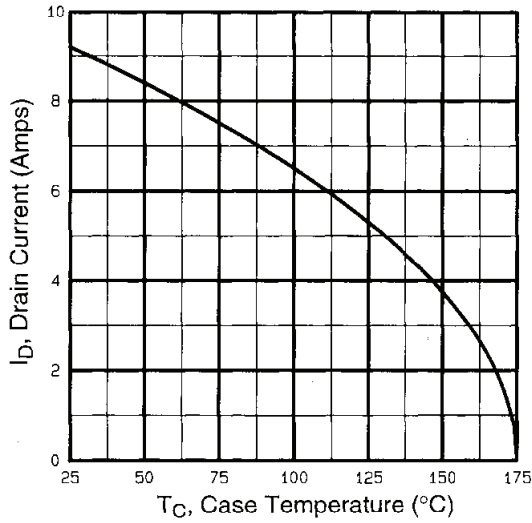


Fig. 9 - Maximum Drain Current vs. Case Temperature

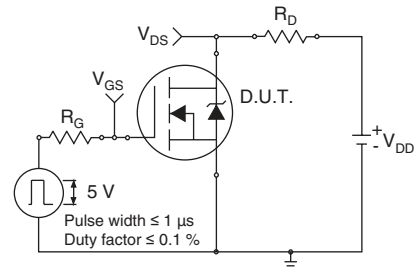


Fig. 10a - Switching Time Test Circuit

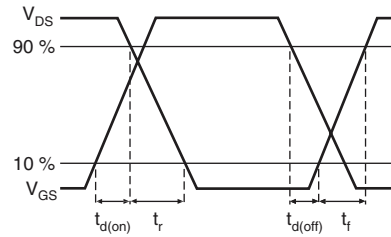


Fig. 10b - Switching Time Waveforms

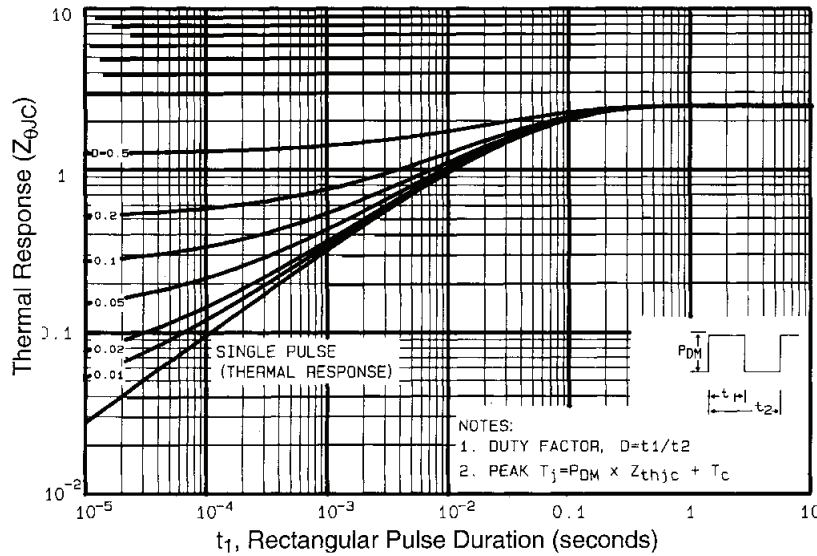


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

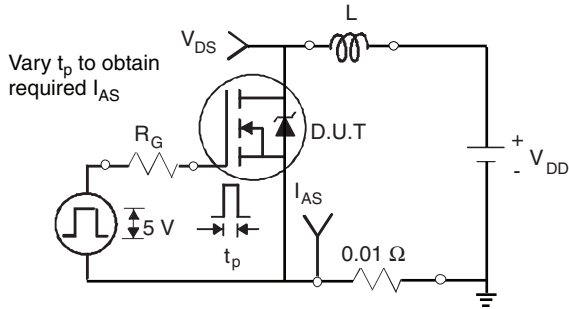


Fig. 12a - Unclamped Inductive Test Circuit

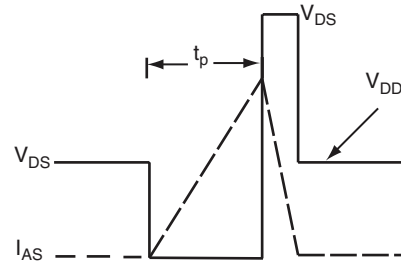


Fig. 12b - Unclamped Inductive Waveforms

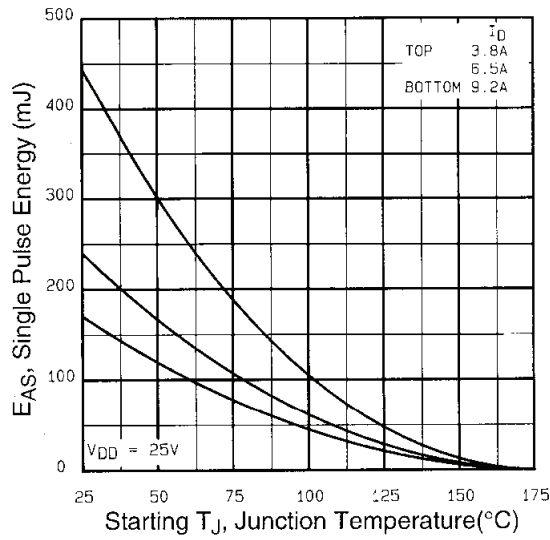


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

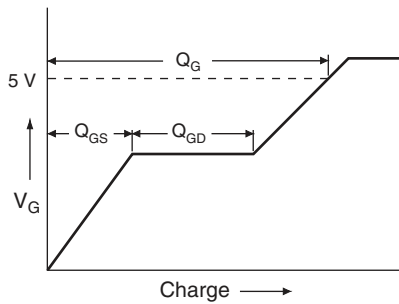


Fig. 13a - Basic Gate Charge Waveform

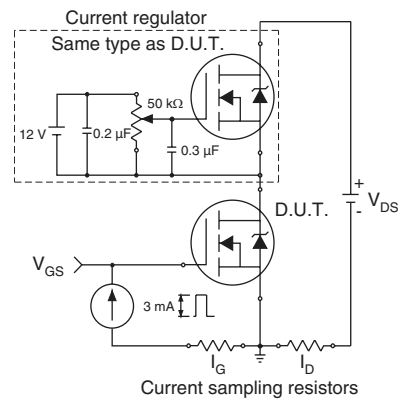
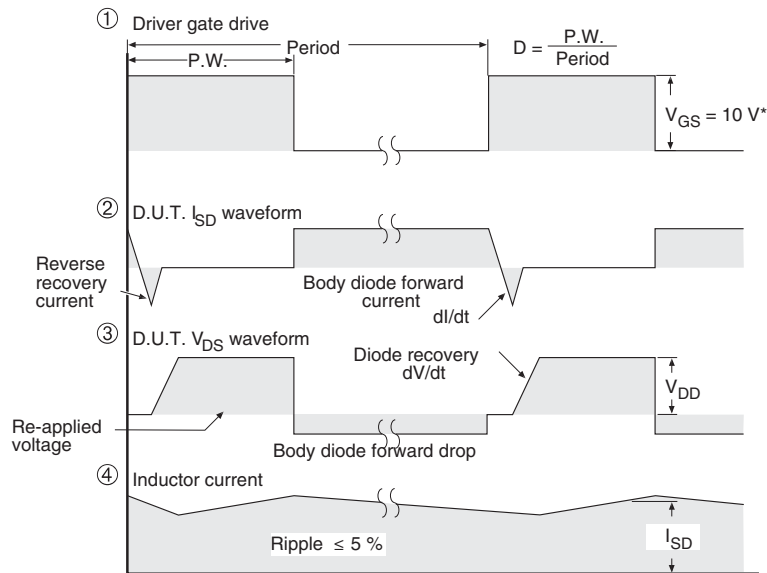
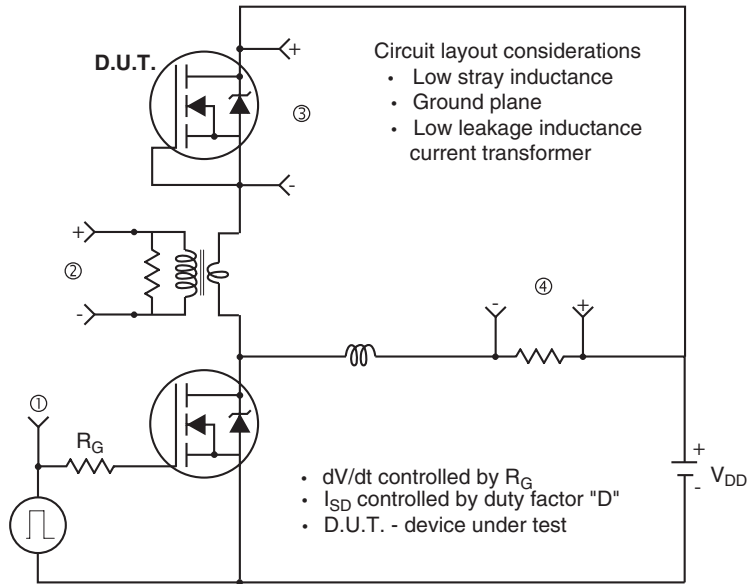


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



* $V_{GS} = 5\text{ V}$ for logic level and 3 V drive devices

Fig. 14 - For N-Channel

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